

REMARKS

INTRODUCTION:

This preliminary amendment is being filed in order to improve the form of the above referenced application. In accordance with the foregoing, a substitute specification, replacement drawings and a new abstract are included in this Preliminary Amendment.

Claims 1, 6, 9-12 and 20-22 have been amended. No new matter is included in this amendment.

CONCLUSION:

There being no outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited. Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters. If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 503333.

Respectfully submitted,

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Date: _____

3/6/06

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For: RECORDED MASTER FOR MANUFACTURING INFORMATION STORAGE MEDIUM
AND METHOD OF MANUFACTURING THE MASTER

SUBSTITUTE SPECIFICATION WITH MARKINGS

TITLE OF THE INVENTION

RECORDED MASTER FOR MANUFACTURING INFORMATION STORAGE MEDIUM AND
METHOD OF MANUFACTURING THE MASTER

CROSS-REFERENCE TO RELATED APPLICATIONS

[0001] This application claims the benefit of PCT International Patent Application

No. PCT/KR2004/002198, filed September 1, 2004, Korean Patent Application No.

2003-62421, filed September 6, 2003, and Korean Patent Application No. 2004-18002, filed

March 17, 2004 in the Korean Intellectual Property Office, the disclosures of which are

incorporated herein by reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

~~Technical Field~~

[0002] The present invention relates to a recorded master for manufacturing an information storage medium and a method of manufacturing the master, and more particularly, to a recorded master for manufacturing an information storage medium in which a pit or groove of a very small size can be formed by chemical and physical reactions between thin films and a stamper can be easily separated by a separation layer, and a method of manufacturing the master.

2. Description of the Related Art

~~Background Art~~

[0003] Generally, an information storage medium is widely employed as an information recording medium in an optical pickup apparatus for recording and/or reproducing information contactlessly. Optical discs as information storage media, are divided into a

compact disc (CD), and a digital versatile disc (DVD) according to the information recording capacity. Optical discs capable of recording, deleting and reproducing information include a 650MB CD-R, CD-RW, 4.7GB DVD+RW, and so on. Furthermore, an HD-DVD with a recording capacity of 20GB or over is also under development.

[0004] Thus, the information storage media are being developed in the direction of increasing a recording capacity. Representative methods to increase a recording capacity include shortening the wavelength of a recording light source and heightening the numerical aperture of an object lens. Also, there is a method of constructing a recording layer as multiple layers.

[0005] Meanwhile, a pit or groove is formed on a substrate in any type of information storage media. As another method of increasing a recording capacity, the pit size or track pitch of a groove can be reduced.

[0006] Capacities of information storage media, pit sizes, and track pitches by generation are shown in the following Table 1:

Table 1

	1st generation	2nd generation	3rd generation
Spec name	CD	DVD	BD
Capacity	650MB	4.7GB	25GB
Laser wavelength	780nm	650nm	405nm
Object lens numerical aperture	0.45	0.6	0.85
Minimum pit size	0.83 μ m	0.40 μ m	0.16 μ m
Track pitch	1.6 μ m	0.74 μ m	0.32 μ m

[0007] As shown in Table 1, with the increasing recording capacity, the pit size and track pitch decrease and technologies to make the pit size and track pitch much smaller are being developed. Here, BD indicates a blue-ray disc.

[0008] Meanwhile, FIG. 1 is a flowchart illustrating a conventional process of manufacturing an information storage medium. The process for manufacturing an information storage medium can be broadly divided into a mastering process and a disc making process. The mastering process is a process for making a stamper from which substrates are injection molded. In the mastering process, a photoresist is coated on a glass substrate in step S10, and exposure is performed by irradiating a laser beam on the photoresist according to a signal corresponding to a mark to be recorded in step S12. Then, by developing the photoresist-coated substrate, a recorded master is made in step S14, and an electrode layer is formed on the glass substrate by Ni sputtering in step S16. Then, metal coating is performed in step S18. On the recorded master, pit shapes and groove shapes are formed.

[0009] Next, the metal coated layer is separated from the recorded master to form a stamper in step S20.

[0010] By using the stamper, a substrate is injection molded in step S22. Then, by sputtering, a recording film is laminated on the injection molded substrate in step S24, and a cover layer is laminated on the recording film in step S26. Through this process, a disc is manufactured in step S28.

[0011] In the manufacturing process, the recording step S12 by irradiating a laser beam can

be regarded as one of the most important factors determining a pit size and a track pitch.

When the size of pit or a track pitch is desired to be reduced in order to increase a recording capacity, the spot size of a laser beam should be reduced. That is, by reducing the wavelength of a laser beam and increasing the numerical aperture, the spot size of a laser beam can be reduced.

SUMMARY OF THE INVENTION

~~{Disclosure}~~

~~Technical Problem~~

[0012] Additional aspects and/or advantages of the invention will be set forth in part in the description which follows and, in part, will be obvious from the description, or may be learned by practice of the invention.

[0013] However, in discs of a generation after the blue-ray disc (BD), laser has a limitation in achieving high density and high capacity recording. Accordingly, a method using an electronic beam having a short wavelength instead of a laser beam are being newly researched and developed. Thus, new research and development is requested in order to satisfy the high density and high capacity recording requirement.

~~Technical Solution~~

[0014] The present invention provides a recorded master for manufacturing an information storage medium in which the size of a pit and the track pitch size of a groove can be reduced simply without a need to make a shorter wavelength laser beam, a separate layer allowing a metal coated layer for a stamper to be separated from a master is disposed to simplify a

manufacturing process, and high density and high capacity recording can be implemented, and a method for manufacturing the master.

[0015] According to an aspect of the present invention, there is provided a recorded master for manufacturing an information storage medium including: a mater substrate; a heat absorption layer which is coated on the mater substrate and absorbs heat at a part on which a beam is irradiated; and a separation layer which is coated on the heat absorption layer, wherein according to the temperature distribution of the part on which the beam is irradiated, volume change occurs in at least one of the heat absorption layer and the separation layer.

[0016] The separation layer may be formed of a photoresist.

[0017] The heat absorption layer is formed of an alloy layer.

[0018] The alloy layer may be formed of a rare earth element metal and a transition metal.

[0019] The alloy layer may be formed of TbFeCo.

[0020] A dielectric layer may be included on at least one of the top and bottom of the heat absorption layer.

[0021] The heat absorption layer may be formed as an alloy dielectric layer formed of a dielectric and an alloy.

[0022] When the melting point of the heat absorption layer is T_1 and the part on which a laser beam is irradiated has a temperature of $0.5T_1$ or over, a volume change may occur in the heat absorption layer and the separation layer part.

[0023] When the melting point of the heat absorption layer is T_1 , the melting point of the separation layer is T_2 , and the temperature distribution of the part on which a laser beam is irradiated is equal to or higher than T_2 and lower than $0.5T_1$, volume change may occur in the separation layer such that a pit is formed.

[0024] When the melting point of the separation layer is T_2 , the glass transition temperature of the separation layer is T_3 , and the temperature distribution of the part on which a laser beam is irradiated is equal to or higher than T_3 and lower than T_2 , a volume change may occur in the separation layer such that a bump is formed.

[0025] According to another aspect of the present invention, there is provided a method for fabricating a recorded master for manufacturing an information storage medium including: coating a heat absorption layer which absorbs heat at a part on a mater substrate on which a beam is irradiated; coating a separation layer on the heat absorption layer; and by irradiating a laser beam on the heat absorption layer, causing volume change in at least one of the heat absorption layer and the separation layer with respect to the temperature distribution of a part on which the beam is irradiated.

~~Advantageous Effects~~

[0026] According to the recorded master for manufacturing an information storage medium of the present invention, by disposing a heat absorption layer and a separation layer in which the volumes change when the layers are heated up to over a predetermined temperature, a pit or a bump is formed such that the size of the pit (or bump) or track pitch can be reduced. By doing so, a high density and high capacity information storage medium can be realized without implementing a high numerical aperture of an object lens and a short wavelength of

a laser beam.

[0027] Furthermore, separation of a stamper from a master can be easily performed and a stamper with a low surface roughness can be provided by using the recorded master according to the present invention. Also, according to the temperature distribution of a part on which a laser beam is irradiated, a pit or a bump can be selectively formed by volume transformation in a heat absorption layer or in a separation layer. In particular, when a pit or a bump is formed by a volume transformation in the separation layer, the depth of the pit or bump can be restricted to the thickness of the separation layer such that the shape of the pit or bump can be easily controlled.

[0028] In addition, the method for manufacturing a recorded master for manufacturing an information storage medium according to the present invention can be performed by using the conventional mastering equipment without change such that the manufacturing cost is low and by using a laser beam of an identical wavelength, the size of a pit or track pitch can be greatly reduced. Also, the stamper can be easily separated from the heat absorption layer such that the manufacturing process can be simplified.

BRIEF DESCRIPTION OF THE DRAWINGS

[0029] These and/or other aspects and advantages of the invention will become apparent and more readily appreciated from the following description of the embodiments, taken in conjunction with the accompanying drawings of which:

~~Description of Drawings~~

~~The above and other features and advantages of the present invention will become more apparent by describing in detail exemplary embodiments thereof with reference to the attached drawings in which:~~

FIG. 1 is a flowchart illustrating a conventional method of manufacturing an information storage medium;

FIG. 2 is a diagram showing the layer structure of a recorded master for manufacturing an information storage medium according to the present invention;

FIG. 3 is a diagram showing a state in which a laser beam is irradiated to a recorded master for manufacturing an information storage medium according to the present invention;

FIG. 4 is a diagram showing a state in which a volume change occurs in a heat absorption layer employed in a recorded master for manufacturing an information storage medium according to the present invention;

FIG. 5 is a diagram showing a state in which a volume change occurs in a separation layer employed in a recorded master for manufacturing an information storage medium according to the present invention such that a pit is formed;

FIG. 6 is a diagram showing a state in which a volume change occurs in a separation layer employed in a recorded master for manufacturing an information storage medium according to the present invention such that a bump is formed;

FIG. 7A is a photo showing an example in which a volume change occurs in a separation layer employed in a recorded master for manufacturing an information storage medium according to the present invention such that a pit is formed;

FIG. 7B is a photo showing an example in which a volume change occurs in a separation layer employed in a recorded master for manufacturing an information storage medium according to the present invention such that a bump type groove is formed;

FIG. 8A is a diagram showing a state in which a coated metal layer is formed on a recorded master for manufacturing an information storage medium according to the present invention;

FIG. 8B is a diagram showing a state in which a coated metal layer is separated from a recorded master for manufacturing an information storage medium according to the present invention; and

FIG. 9 is a flowchart illustrating a mastering process of a recorded master for manufacturing an information storage medium according to the present invention.

DETAILED DESCRIPTION OF THE EMBODIMENTS

[0030] Reference will now be made in detail to the present embodiments of the present invention, examples of which are illustrated in the accompanying drawings, wherein like reference numerals refer to the like elements throughout. The embodiments are described below in order to explain the present invention by referring to the figures.

~~Mode for Invention~~

~~The present invention will now be described more fully with reference to the accompanying drawings, in which exemplary embodiments of the invention are shown.~~

[0031] Referring to FIG. 2, a recorded master 5 for manufacturing an information storage medium according to the present invention includes a heat absorption layer 15 coated on a mater substrate 10, and a separation layer 20 coated on the heat absorption layer 15.

[0032] The heat absorption layer 15 absorbs heat when a beam is irradiated, hereon and a volume change occurs in the part on which the beam is irradiated, or volume change occurs in the separation layer 20. That is, in the heat absorption layer 15, a chemical and physical reaction occurs according to temperature distribution and causes volume change in the heat absorption layer 15 itself or causes volume change only in the separation layer 20.

[0033] The heat absorption layer 15 can be formed as an alloy dielectric layer, which is formed of a dielectric and an alloy, or an alloy layer. Here, the alloy (or the alloy layer) can be formed by including rare earth element metals and transition metals, and the rare earth element metals include Tb and the transition metals may include Fe and Co.

[0034] A dielectric layer can be disposed at least one of the top and bottom of the heat absorption layer 15. FIG. 2 shows a case where a first dielectric layer 11 and a second dielectric layer 12 are disposed on the top and bottom of the heat absorption layer 15, respectively.

[0035] The first and second dielectric layers 11 and 13 can be formed by including a mixture of ZnS and SiO₂. Preferably, the heat absorption layer is formed of TbFeCo and the first and second dielectric layers 11 and 13 can be formed of ZnS-SiO₂.

[0036] The separation layer 20 is laminated on the heat absorption layer 15 such that a stamper (Refer to 30 of FIG. 8A) to be explained later can be easily separated from the heat absorption layer 15. The separation layer 20 can be formed of, for example, photoresist. Also, due to the volume change in the heat absorption layer 15, the volume of the separation layer 20 may change together with the heat absorption layer 15, or may change alone.

[0037] Referring to FIG. 3, since a laser beam (L) has a Gaussian distribution, the optical intensity of the central part is relatively stronger than the edge part of the laser beam. Accordingly, if a laser beam is irradiated on the heat absorption layer 15, the temperature of an area on which the central part of the laser beam is irradiated becomes higher than that of an area on which the edge part of the laser beam is irradiated. The laser beam (L) is focused on the heat absorption layer 15 through an object lens (OL).

[0038] While the recorded master 5 rotates, the laser beam (L) is irradiated on the recorded master 5. At this time, the temperature distribution of an exposed part at the heat absorption layer 15 changes with respect to the linear velocity of the recorded master 5 and

the power of the laser beam. According to this temperature distribution, a volume change occurs in at least one of the heat absorption layer 15 and the separation layer 20.

[0039] Assuming that the melting point of the heat absorption layer 15 is T_1 , the melting point of the separation layer 20 is T_2 , and the glass transition temperature of the separation layer 20 is T_3 , if the heat absorption layer 15 is heated up to a temperature in the vicinity of T_1 , the reaction of the heat absorption layer 15 and dielectric layers causes a volume transformation in the heat absorption layer 15 and according to this, a transformation occurs also in the first and second dielectric layers 11 and 13 and the separation layer 20.

[0040] When a recording condition causing a transformation is simulated, a temperature at in which forming of a protrusion part is possible is equal to or over $0.5T_1$.

[0041] In other words, a volume change occurs in the part (B) of the heat absorption layer 15 heated up to the vicinity of a predetermined temperature (T_1), and a protrusion part 25 as shown in FIG. 4 is formed. This protrusion part 25 becomes a bump or a groove.

Hereinafter, a bump will be referred to by reference number 25.

[0042] Next, when the temperature of a part on which a beam is irradiated is substantially lower than T_1 , the reaction between thin films does not occur. Accordingly, as shown in FIG. 5, a volume transformation occurs not in the heat absorption layer 15, but only in the separation layer 20 such that a pit 26 is formed. Here, the temperature of a part on which a beam is irradiated is heated up to a temperature equal to or over T_2 and lower than $0.5T_1$, and a pit 26 is formed.

[0043] Meanwhile, if the temperature of a part on which a beam is irradiated is equal to or

higher than T3 and lower than T2, as shown in FIG. 6, volume transformation occurs in the separation layer 20 such that a bump 25' is formed. Also at this time, a volume transformation occurs not in the heat absorption layer 15, but occurs only in the separation layer 20. While the pit 26 is formed in FIG. 5, a bump 25' is formed in FIG. 6. When the pit 26 or the bump 25' is formed by the volume transformation in the separation layer 20, the depth of the pit 26 or the height of the bump 25' is limited to the thickness of the separation layer 20. Accordingly, there is an advantage in that the height or depth does not need to be controlled separately.

[0044] As described above, with respect to the temperature of a part on which a beam is irradiated, layers where a volume transformation occurs and the shape of volume transformation change.

[0045] More specifically, a heat absorption layer formed of TbFeCo of a 15nm thickness, a dielectric layer of a 15nm thickness, and a separation layer formed of photoresist of a 50nm thickness are sequentially laminated on a mater substrate and information is recorded by irradiating a laser beam. Here, the glass transition temperature of the photoresist is 110-130°C, the melting point of the photoresist is 200-220°C, and the melting point of TbFeCo layer is approximately 1440°C.

[0046] At this time, data was recorded by using a laser beam having a 405nm wavelength, 10MHz pulse, and 13mW recording power, and a recording condition of a 6m/sec linear velocity, and a photo of the result is shown in FIG. 7A. According to the photo, a pit 26 is formed in a separation layer and the depth is 30nm that is the thickness of

the photoresist. Also, the size of the pit formed at this time is approximately 150nm. This size cannot be manufactured by the conventional mastering method. Under the conditions described above, it is difficult to measure the temperature of a part on which a laser beam was irradiated, but according to temperature calculation by simulation, the temperature is approximately 400°C.

[0047] Next, when the linear velocity is 6m/sec and the recording power is 10mW, the temperature of an exposed part is approximately 200°C, and in this temperature distribution, a bump (25') type groove is formed as shown in FIG. 7B.

[0048] As shown in FIG. 8A, an electrode layer 27 is laminated on the separation layer 20 and by using this, a metal coated layer 28 is formed. Then, as shown in FIG. 8B, the electrode layer 27 and the metal coated layer 28 are separated from the master 5. Thus, the separated electrode layer 27 and the metal coated layer 28 become a stamper 30.

[0049] At this time, by using a solution capable of melting only the separation layer 20 not affecting the metal coated layer 28, the stamper 30 can be easily separated.

[0050] For example, when the separation layer 20 is formed of a photoresist, separation can be easily performed by melting the photoresist.

[0051] When the stamper 30 is separated from the separation layer 20, the separation layer 20 may not be removed completely and part of the separation layer 20 may remain on the second dielectric layer 13 or on the electrode layer 27. However, even when part of the separation layer 20 remains on either side, the photoresist can be removed easily such that there is no particular difficulty in the manufacturing process. Also, when the separation

layer 20 is formed of, for example, a liquid photoresist, the surface of the separation layer 20 is very smooth and the surface shape of this separation layer 20 is directly transferred to the stamper 30. Accordingly, there is an advantage in that the surface roughness of the stamper 30 is greatly reduced.

[0052] Though the pit 26 formed by the volume transformation in the heat absorption layer 15 is shown in FIGS. 8A and 8B, the method for manufacturing a stamper is identical even when the bump 25' is formed.

[0053] Thus, the stamper 30 required for injection molding a substrate of an information storage medium is completed. If a substrate is injection molded by using this stamper, the shape of a pit, groove or bump is transferred on the substrate. By sequentially laminating a recording film and a cover layer on this substrate, an information storage medium is manufactured.

[0054] Next, referring to FIGS. 2 and 9, in a method for manufacturing a recorded master for manufacturing an information storage medium, the heat absorption layer 15 is coated on the mater substrate 10 in step S20 and the separation layer 20 is coated on the heat absorption layer 15 in step S22.

[0055] The heat absorption layer 15 has a characteristic that when the heat absorption layer 15 is heated over a predetermined temperature, a physical and chemical reaction occurs. According to the temperature distribution of a part on which a beam is irradiated, volume transformation occurs in at least one of the heat absorption layer 15 and the separation layer 20 and a pit or a bump is formed.

[0056] The temperature of the part on which a beam is irradiated depends on the power of a laser beam or the linear velocity of the master.

[0057] As described above, the heat absorption layer is formed of the first dielectric layer 11, the alloy layer 12, and the second dielectric layer 13, or formed as an alloy dielectric layer.

[0058] Preferably, the alloy layer 12 is formed of a rare earth element metal and a transition metal, and the rare earth element metal includes Tb and the transition metal includes iron (Fe) and cobalt (Co).

[0059] If a laser beam is irradiated on the heat absorption layer 15 in step S24, a part which is heated up over a predetermined temperature in the part on which the laser beam is irradiated swells and a pit (or groove) or a bump is formed. Here, since the laser beam has a Gaussian distribution, the size of the part which is heated up over the predetermined temperature and swells can be minimized. That is, when a laser beam of an identical wavelength and an object lens of an identical numerical aperture are used, a valid spot size of a laser beam can be reduced compared to the conventional manufacturing method. Here, the valid spot size means a spot size which is practically used to form a pit.

[0060] Though a laser beam is irradiated after the separation layer 20 is coated on the heat absorption layer 15 in the above explanation, a laser beam may be irradiated on the heat absorption layer 15 before laminating the separation layer 20 on the heat absorption layer 15 to form a pit or a groove, and then the separation layer 20 can be coated on the heat absorption layer 15. This method is applied when a volume transformation occurs in

the heat absorption layer 15.

[0061] Then, the electrode layer 27 for metal coating is formed on the separation layer 20 in step S26, and by using the electrode layer 27, the metal coated layer 28 is formed in step S28. Then, the bump (or groove) 25 or 25' or the pit 26 formed by volume transformation in at least one of the heat absorption layer 15 and the separation is transferred.

[0062] Next, by removing the separation layer 20, the electrode layer 27 and the metal coated layer 28 are separated from the master 5. When the separation layer 20 is formed by a photoresist, it can be easily removed from the master 5. By doing so, the stamper 30 for injection molding a substrate can be obtained in step S30.

[0063] Depending on whether or not a pit shape remains on the second dielectric layer 13 when the separation layer 20 is removed, it can be confirmed whether volume transformation occurs in the heat absorption layer or the separation layer 20.

[0064] Meanwhile, by varying the thicknesses of the heat absorption layer and the separation layer, the effects of those layers were tested. Here, the first and second dielectric layers 11 and 13 formed of ZnS-SiO₂ and the alloy layer 12 formed of TbFeCo were coated on the glass substrate 10 by sputtering and the separation layer 20 was formed by spin coating positive type photoresist. Then, the thicknesses of the first and second dielectric layers 11 and 13, the alloy layer 12 and the separation layer 20 were transformed as the following table 2:

Table 2

		Thickness (nm)			
		sample 1	sample 2	sample 3	sample 4
1st dielectric layer	ZnS-SiO ₂	170	170	170	170
Alloy layer	TbFeCo	15	15	15	15
2nd dielectric layer	ZnS-SiO ₂	15	15	15	15
Photoresist	Positive type	0	25	50	100

[0065] On the substrate prepared as presented in Table 2, a blue laser was irradiated and a pulse of 15MHz was input as a recording signal at a linear velocity of 3 m/sec. After recording by irradiating a laser beam, an electrode layer was spread to the thickness of approximately 100nm, by sputtering, and a stamper was formed by metal coating. After metal coating, whether or not the stamper was separated (separation) was confirmed, and after making the stamper, the depth of a pit was measured. Separation of the stamper was performed mainly between the separation layer and the electrode layer. When a small amount of the separation layer remained on the stamper, it could be easily removed by NaOH aqueous solution.

[0066] The test result of the depths of pits formed by varying the thickness of the heat absorption layer and the separation layer as in Table 2 and separation are shown in Table 3:

Table 3

Number	Sample	Pit depth (nm)	Separation
1		65	Not separated
2		60	Separable
3		50	Separable
4		30	Separable

[0067] According to the results in Table 3, when there was no separation layer (sample 1), it was impossible to separate the stamper from the heat absorption layer, and accordingly, it can be seen that the stamper cannot be manufactured normally.

[0068] Meanwhile, when there was the separation layer, it can be seen that separation of the stamper is possible regardless of the thickness of the separation layer.

[0069] Thus by simply coating the separation layer on the heat absorption layer, the stamper for manufacturing an information storage medium can be easily manufactured.

[0070] Although a few embodiments of the present invention have been shown and described, it would be appreciated by those skilled in the art that changes may be made in this embodiment without departing from the principles and spirit of the invention, the scope of which is defined in the claims and their equivalents.